

CMOS 8-Stage Presettable Synchronous Down Counters

High-Voltage Types (20-Volt Rating)

CD40102B – 2-Decade BCD Type

CD40103B – 8-Bit Binary Type

■ CD40102B, and CD40103B consist of an 8-stage synchronous down counter with a single output which is active when the internal count is zero. The CD40102B is configured as two cascaded 4-bit BCD counters, and the CD40103B contains a single 8-bit binary counter. Each type has control inputs for enabling or disabling the clock, for clearing the counter to its maximum count, and for presetting the counter either synchronously or asynchronously. All control inputs and the CARRY-OUT/ZERO-DETECT output are active-low logic.

In normal operation, the counter is decremented by one count on each positive transition of the CLOCK. Counting is inhibited when the CARRY-IN/COUNTER ENABLE ($\overline{CI/CE}$) input is high. The CARRY-OUT/ZERO-DETECT ($\overline{CO/ZD}$) output goes low when the count reaches zero if the $\overline{CI/CE}$ input is low, and remains low for one full clock period.

When the SYNCHRONOUS PRESET-ENABLE ($\overline{SPE}$) input is low, data at the JAM input is clocked into the counter on the next positive clock transition regardless of the state of the $\overline{CI/CE}$ input. When the ASYNCHRONOUS PRESET-ENABLE ($\overline{APE}$) input is low, data at the JAM inputs is asynchronously forced into the counter regardless of the state of the $\overline{SPE}$, $\overline{CI/CE}$, or CLOCK inputs. JAM inputs J0-J7 represent two 4-bit BCD words for the CD40102B and a single 8-bit binary word for the CD40103B.

When the CLEAR ($\overline{CLR}$) input is low, the counter is asynchronously cleared to its maximum count (99₁₀ for the CD40102B and 255₁₀ for the CD40103B) regardless of the state of any other input. The precedence relationship between control inputs is indicated in the truth table.

If all control inputs except $\overline{CI/CE}$ are high at the time of zero count, the counters will jump to the maximum count, giving a counting sequence of 100 or 256 clock pulses long.

This causes the $\overline{CO/ZD}$ output to go low to enable the clock on each succeeding clock pulse.

The CD40102B and CD40103B may be cascaded using the $\overline{CI/CE}$ input and the $\overline{CO/ZD}$ output, in either a synchronous or ripple mode as shown in Figs.21 and 22.

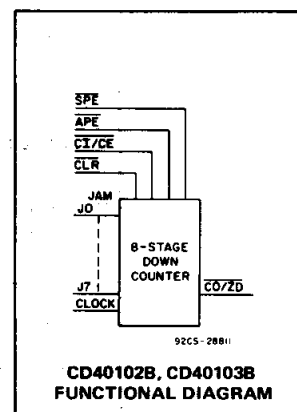
The CD40102B and CD40103B types are supplied in 16-lead dual-in-line plastic packages (E suffix), 16-lead small-outline packages (NSR suffix), and 16-lead thin shrink small-outline packages (PW and PWR suffixes). The CD40103B types also are supplied in 16-lead hermetic dual-in-line ceramic packages (F3A suffix).

Features:

- Synchronous or asynchronous preset
- Medium-speed operation: $f_{CL} = 3.6 \text{ MHz (typ.) @ } V_{DD} = 10 \text{ V}$
- Cascadable
- 100% tested for quiescent current at 20 V
- Maximum input current of 1 μA at 18 V over full package-temperature range; 100 nA at 18 V and 25°C
- Noise margin (full package-temperature range) = 1 V at $V_{DD} = 5 \text{ V}$
2 V at $V_{DD} = 10 \text{ V}$
2.5 V at $V_{DD} = 15 \text{ V}$
- Standardized, symmetrical output characteristics
- 5-V, 10-V, and 15-V parametric ratings
- Meets all requirements of JEDEC Tentative Standard No. 13B, "Standard Specifications for Description of 'B' Series CMOS Devices"

Applications:

- Divide-by-"N" counters
- Programmable timers
- Interrupt timers
- Cycle/program counter



RECOMMENDED OPERATING CONDITIONS AT $T_A = 25^\circ\text{C}$, Unless Otherwise Specified

For maximum reliability, nominal operating conditions should be selected so that operation is always within the following ranges.

Characteristic	V_{DD}	LIMITS		Units
		Min.	Max.	
Supply Voltage Range (At $T_A = \text{Full Package-Temperature Range}$)		3	18	V
Clock Pulse Width, t_W	5	300	—	ns
	10	180	—	
	15	80	—	
$\overline{\text{Clear}}$ Pulse Width, t_W	5	320	—	ns
	10	160	—	
	15	100	—	
$\overline{\text{APE}}$ Pulse Width, t_W	5	360	—	ns
	10	160	—	
	15	120	—	
Clock Input Frequency, f_{CL}	5	—	0.7	MHz
	10	—	1.8	
	15	—	2.4	
Clock Rise and Fall Time, t_{rCL} , t_{fCL}	5	—	—	μs
	10	—	15	
	15	—	—	
$\overline{\text{SPE}}$ Setup Time, t_{SU}	5	280	—	ns
	10	140	—	
	15	100	—	
Jam Setup Time, t_{SU}	5	200	—	ns
	10	80	—	
	15	60	—	
$\overline{\text{CI/CE}}$ Setup Time, t_{SU}	5	500	—	ns
	10	250	—	
	15	150	—	

CD40102B, CD40103B Types

MAXIMUM RATINGS, Absolute-Maximum Values:

DC SUPPLY-VOLTAGE RANGE, (V_{DD})

Voltages referenced to V_{SS} Terminal)

INPUT VOLTAGE RANGE, ALL INPUTS -0.5V to +20V

DC INPUT CURRENT, ANY ONE INPUT -0.5V to $V_{DD}+0.5V$

POWER DISSIPATION PER PACKAGE (P_D):

For $T_A = -55^\circ\text{C}$ to $+100^\circ\text{C}$ 500mW

For $T_A = +100^\circ\text{C}$ to $+125^\circ\text{C}$ Derate Linearly at 12mW/ $^\circ\text{C}$ to 200mW

DEVICE DISSIPATION PER OUTPUT TRANSISTOR

FOR $T_A = \text{FULL PACKAGE-TEMPERATURE RANGE (All Package Types)}$ 100mW

OPERATING-TEMPERATURE RANGE (T_A) -55 $^\circ\text{C}$ to +125 $^\circ\text{C}$

STORAGE TEMPERATURE RANGE (T_{stg}) -65 $^\circ\text{C}$ to +150 $^\circ\text{C}$

LEAD TEMPERATURE (DURING SOLDERING):

At distance 1/16 $\pm$ 1/32 inch (1.59 $\pm$ 0.79mm) from case for 10s max +265 $^\circ\text{C}$

STATIC ELECTRICAL CHARACTERISTICS

CHARACTER- ISTIC	CONDITIONS			LIMITS AT INDICATED TEMPERATURES (°C)							UNITS
	V _O (V)	V _{IN} (V)	V _{DD} (V)	+25							
				-55	-40	+85	+125	Min.	Typ.	Max.	
Quiescent Device Current, I _{DD} Max.	—	0,5	5	5	5	150	150	—	0.04	5	μA
	—	0,10	10	10	10	300	300	—	0.04	10	
	—	0,15	15	20	20	600	600	—	0.04	20	
	—	0,20	20	100	100	3000	3000	—	0.08	100	
Output Low (Sink) Current I _{OL} Min.	0.4	0,5	5	0.64	0.61	0.42	0.36	0.51	1	—	mA
	0.5	0,10	10	1.6	1.5	1.1	0.9	1.3	2.6	—	
	1.5	0,15	15	4.2	4	2.8	2.4	3.4	6.8	—	
Output High (Source) Current, I _{OH} Min.	4.6	0,5	5	-0.64	-0.61	-0.42	-0.36	-0.51	-1	—	mA
	2.5	0,5	5	-2	-1.8	-1.3	-1.15	-1.6	-3.2	—	
	9.5	0,10	10	-1.6	-1.5	-1.1	-0.9	-1.3	-2.6	—	
	13.5	0,15	15	-4.2	-4	-2.8	-2.4	-3.4	-6.8	—	
Output Voltage: Low-Level, V _{OL} Max.	—	0,5	5	0.05				—	0	0.05	V
	—	0,10	10	0.05				—	0	0.05	
	—	0,15	15	0.05				—	0	0.05	
Output Voltage: High-Level, V _{OH} Min.	—	0,5	5	4.95				4.95	5	—	V
	—	0,10	10	9.95				9.95	10	—	
	—	0,15	15	14.95				14.95	15	—	
Input Low Voltage, V _{IL} Max.	0.5, 4.5	—	5	1.5				—	—	1.5	V
	1, 9	—	10	3				—	—	3	
	1.5,13.5	—	15	4				—	—	4	
Input High Voltage, V _{IH} Min.	0.5, 4.5	—	5	3.5				3.5	—	—	V
	1, 9	—	10	7				7	—	—	
	1.5,13.5	—	15	11				11	—	—	
Input Current I _{IN} Max.	—	0,18	18	±0.1	±0.1	±1	±1	—	±10 ⁻⁵	±0.1	μA

Note 1: These parameters and limits also apply to the Synchronous Preset Mode should a Preset condition of JAM Zero on J_0 to J_7 exist.

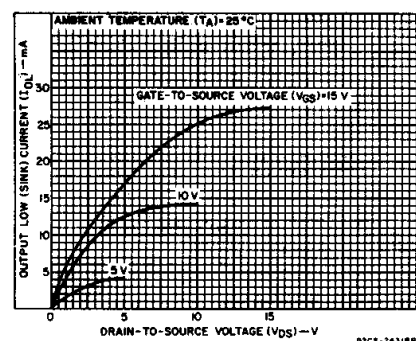


Fig. 1 — Typical output low (sink) current characteristics.

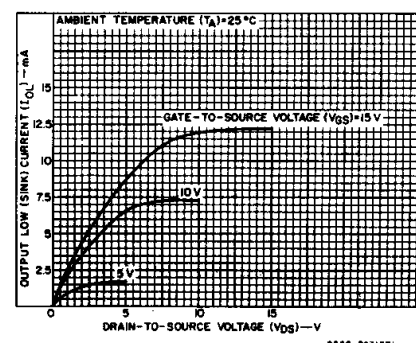


Fig. 2 — Minimum output low (sink) current characteristics.

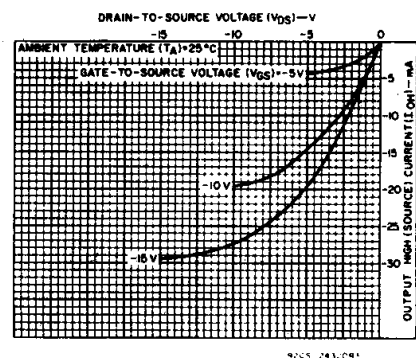


Fig. 3 — Typical output high (source) current characteristics.

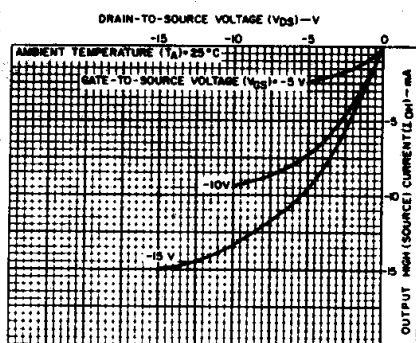


Fig. 4 — Minimum output high (source) current characteristics.

CD40102B, CD40103B Types

DYNAMIC ELECTRICAL CHARACTERISTICS at $T_A = 25^\circ\text{C}$, $C_L = 50\text{ pF}$,
Input $t_r, t_f = 20\text{ ns}$, $R_L = 200\text{ k}\Omega$

Characteristic	Conditions V_{DD} (V)	Limits All Packages			Units
		Min.	Typ.	Max.	
Propagation Delay Time (t_{PHL}, t_{PLH}):					
Clock-to-Output (See Fig. 6)	5	—	300	600	ns
Note 1	10	—	130	260	
	15	—	95	190	
Carry In/Counter Enable-to-Output	5	—	200	400	ns
	10	—	90	180	
	15	—	65	130	
Asynchronous Preset Enable-to-Output	5	—	650	1300	ns
Note 1	10	—	300	600	
	15	—	200	400	
Clear-to-Output	5	—	375	750	ns
	10	—	180	360	
	15	—	100	200	
Transition Time (t_{THL}, t_{TLH})	5	—	100	200	ns
	10	—	50	100	
	15	—	40	80	
Minimum Clock Pulse Width, (t_W)	5	—	150	300	ns
	10	—	90	180	
	15	—	40	80	
Minimum CLR Pulse Width (t_W)	5	—	160	320	ns
	10	—	80	160	
	15	—	50	100	
Minimum APE Pulse Width (t_W)	5	—	180	360	ns
	10	—	80	160	
	15	—	60	120	
Minimum APE Removal Time (t_{RM})	5	—	110	220	ns
	10	—	50	100	
	15	—	35	70	
Minimum SPE Set-Up Time (t_{SU})	5	—	140	280	ns
	10	—	70	140	
	15	—	50	100	
Minimum CI/CE Setup Time (t_{SU})	5	—	250	500	ns
	10	—	125	250	
	15	—	75	150	
Minimum JAM Set-Up Time (t_{SU}) (Synchronous presetting)	5	—	100	200	ns
	10	—	40	80	
	15	—	30	60	
Maximum Clock Input Frequency (f_{CL}) (See Fig. 7)	5	0.7	1.4	—	MHz
	10	1.8	3.6	—	
	15	2.4	4.8	—	
Input Capacitance (C_{IN})		—	5	7.5	pF

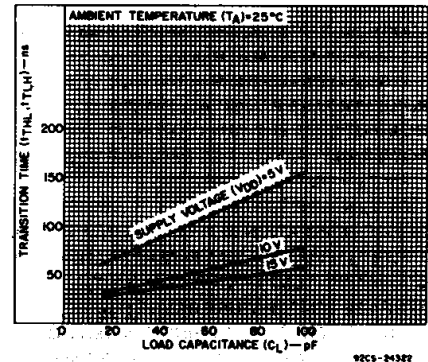


Fig. 5 - Typical transition time as a function of load capacitance.

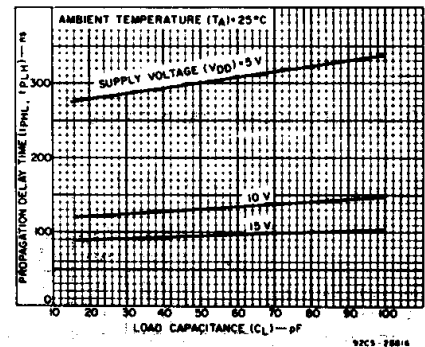


Fig. 6 - Typical propagation delay time as a function of load capacitance (clock to CO/ZD).

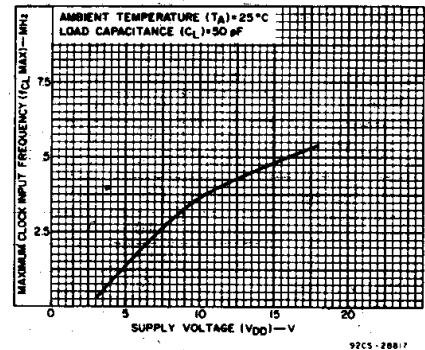


Fig. 7 - Typical maximum clock input frequency as a function of supply voltage.

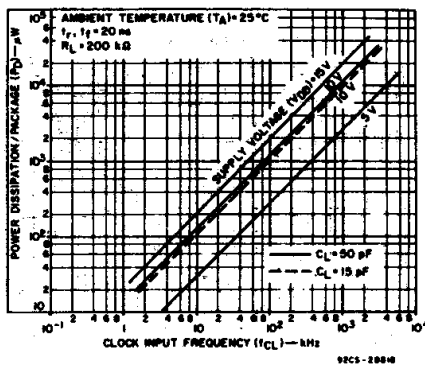


Fig. 8 - Typical dynamic power dissipation as a function of frequency.

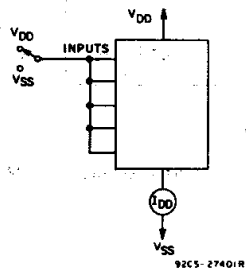


Fig. 9 - Quiescent device current test circuit.

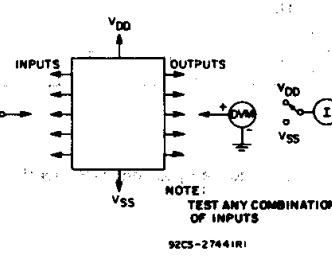


Fig. 10 - Input voltage test circuit.

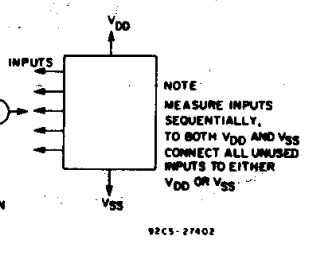


Fig. 11 - Input current test circuit.

CD40102B, CD40103B Types

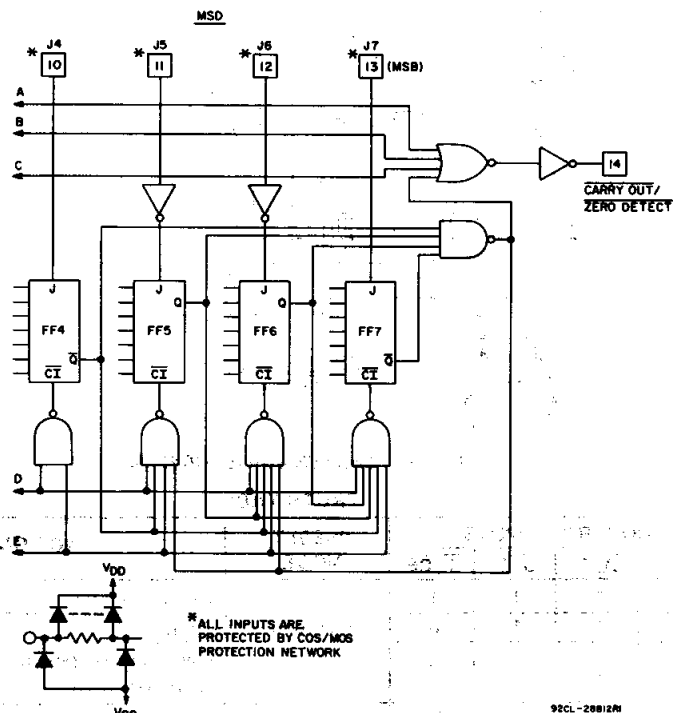
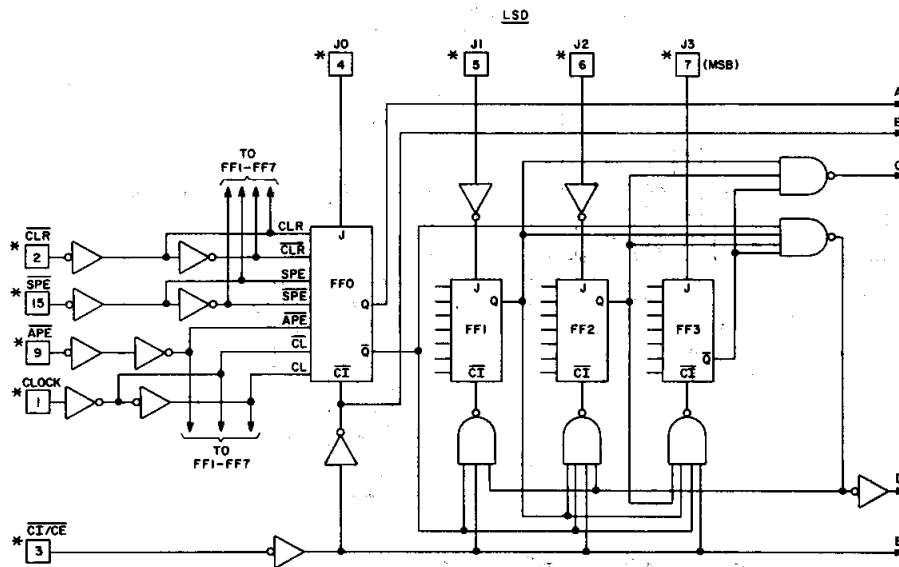


Fig. 12 — Logic diagram for CD40102B.

CD40102B, CD40103B Types

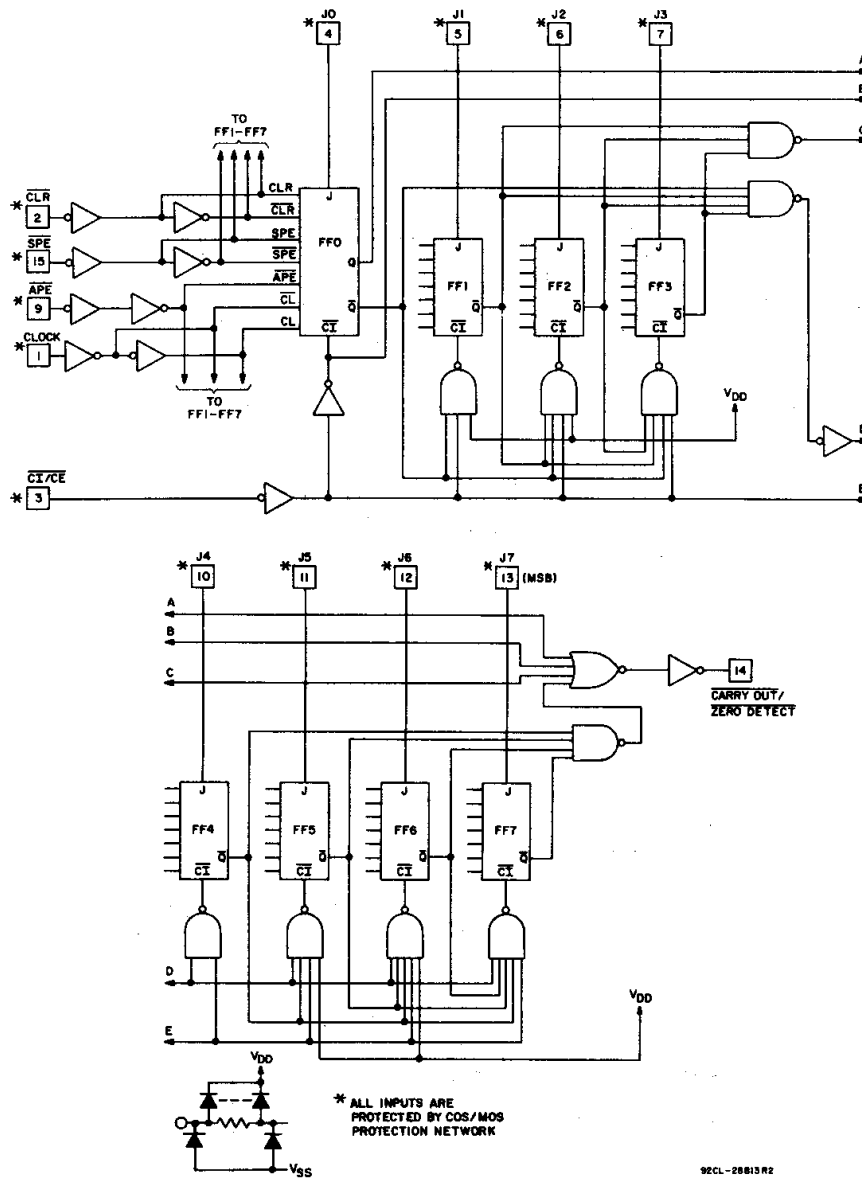


Fig. 13 — Logic diagram for CD40103B.

TRUTH TABLE

CONTROL INPUTS				PRESET MODE	ACTION
CLR	APE	SPE	CI/CE		
1	1	1	1	Synchronous	Inhibit counter
1	1	1	0		Count down*
1	1	0	X		Preset on next positive clock transition
1	0	X	X	Asynchronous	Preset asynchronously
0	X	X	X		Clear to maximum count

Notes: 1. 0 = Low level
1 = High level
X = Don't care

- Clock connected to clock input
- Synchronous operation: changes occur on negative-to-positive clock transitions
- JAM inputs: CD40102B BCD; MSD = J7,J6,J5,J4 (J7 is MSB)
LSD = J3,J2,J1,J0 (J3 is MSB)
CD40103B Binary; MSB = J7, LSB = J0

*At zero count, the counters will jump to the maximum count on the next clock transition to "High."

CD40102B, CD40103B Types

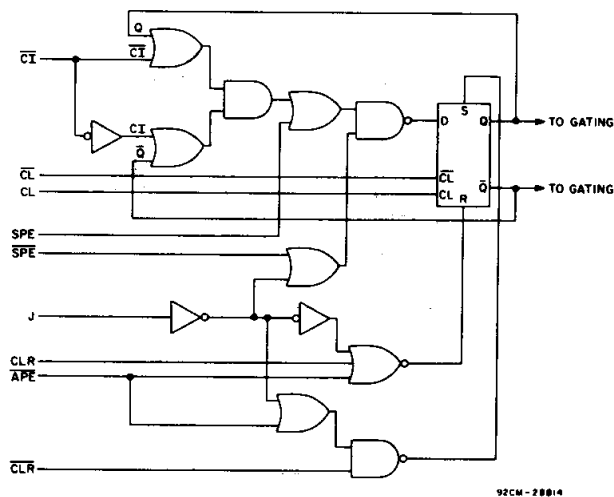


Fig. 14 - Detail logic diagram for flip-flops, FFO - FF7, used in logic diagrams for CD40102B and CD40103B.

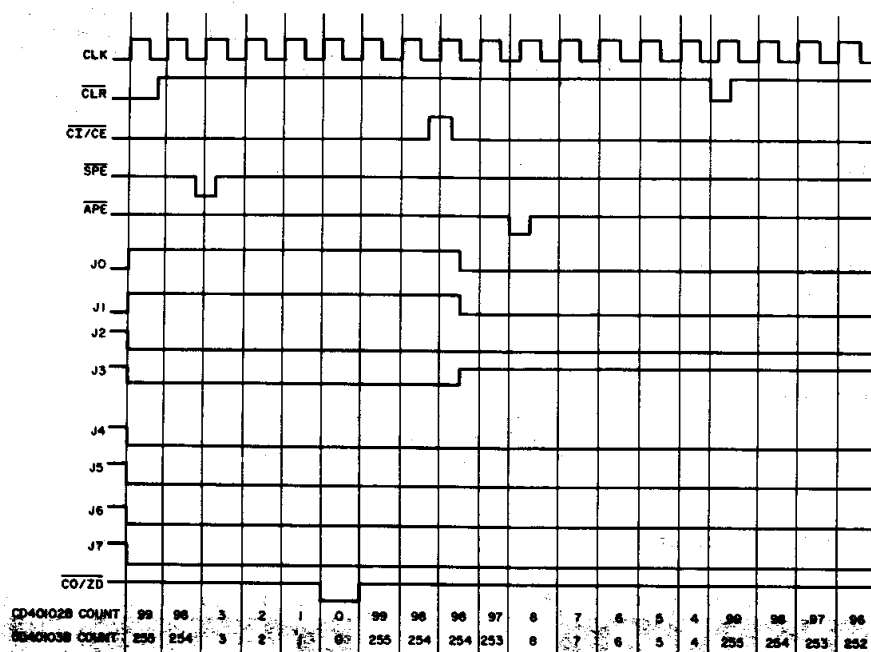
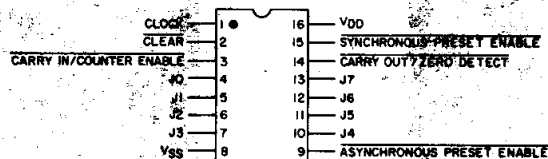


Fig. 15 - Timing diagram for CD40102B and CD40103B.



CD40102B,
CD40103B
TERMINAL ASSIGNMENT

CD40102B, CD40103B Types

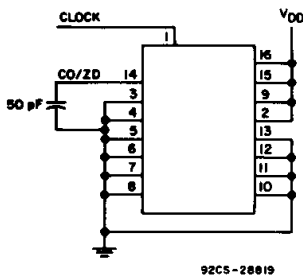


Fig. 16 - Maximum clock frequency test circuit.

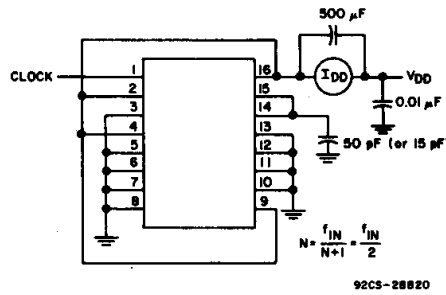


Fig. 17 - Dynamic power dissipation test circuit ($\div 2$ mode).

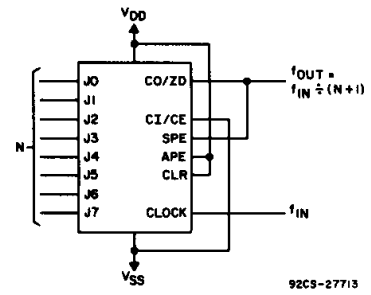


Fig. 18 - Divide-by-"N" counter.

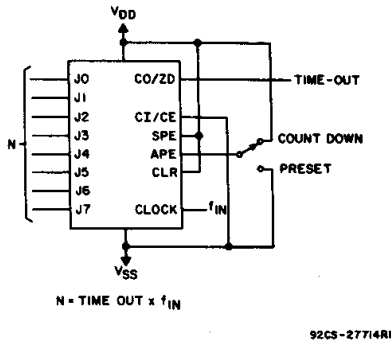


Fig. 19 - Programmable timer.

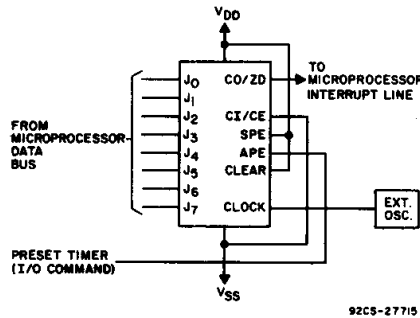


Fig. 20 - Microprocessor interrupt timer.

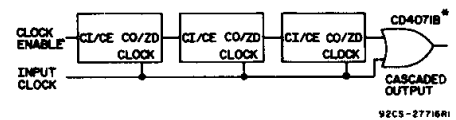


Fig. 21 - Synchronous cascading.

* An output spike (160 ns @ $V_{DD} = 5$ V) occurs whenever two or more devices are cascaded in the parallel-clocked mode because the clock-to-carry out delay is greater than the carry-in-to-carry out delay. This spike is eliminated by gating the output of the last device with the clock as shown.

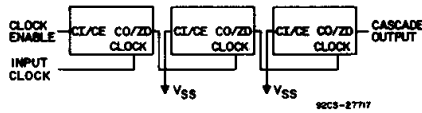
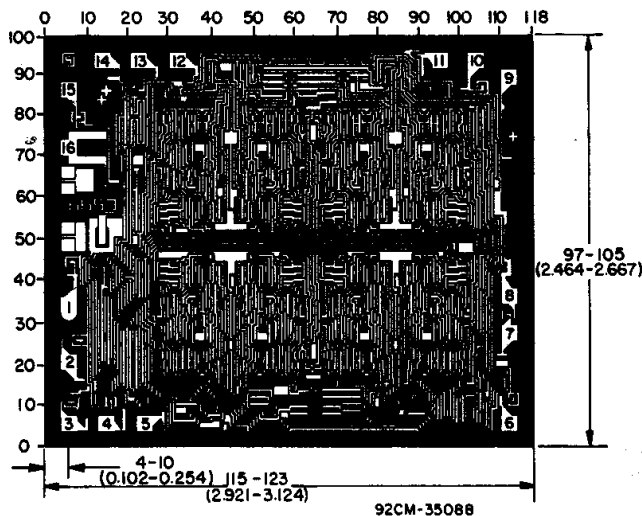


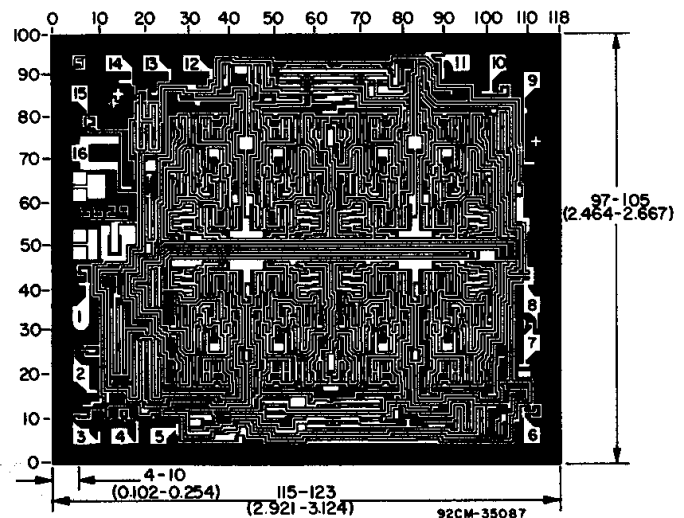
Fig. 22 - Ripple cascading.

Dimensions in parentheses are in millimeters and are derived from the basic inch dimensions as indicated. Grid graduations are in mils (10^{-3} inch).

Dimensions and pad layout for CD40102B.



Dimensions and pad layout for CD40103B.



PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package Pins	Package qty Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
CD40102BE	Active	Production	PDIP (N) 16	25 TUBE	Yes	NIPDAU	N/A for Pkg Type	-55 to 125	CD40102BE
CD40102BE.A	Active	Production	PDIP (N) 16	25 TUBE	Yes	NIPDAU	N/A for Pkg Type	-55 to 125	CD40102BE
CD40102BNSR	Active	Production	SOP (NS) 16	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-55 to 125	CD40102B
CD40102BNSR.A	Active	Production	SOP (NS) 16	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-55 to 125	CD40102B
CD40102BPW	Obsolete	Production	TSSOP (PW) 16	-	-	Call TI	Call TI	-55 to 125	CM0102B
CD40102BPWR	Active	Production	TSSOP (PW) 16	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-55 to 125	CM0102B
CD40102BPWR.A	Active	Production	TSSOP (PW) 16	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-55 to 125	CM0102B
CD40103BE	Active	Production	PDIP (N) 16	25 TUBE	Yes	NIPDAU	N/A for Pkg Type	-55 to 125	CD40103BE
CD40103BE.A	Active	Production	PDIP (N) 16	25 TUBE	Yes	NIPDAU	N/A for Pkg Type	-55 to 125	CD40103BE
CD40103BEE4	Active	Production	PDIP (N) 16	25 TUBE	Yes	NIPDAU	N/A for Pkg Type	-55 to 125	CD40103BE
CD40103BF	Active	Production	CDIP (J) 16	25 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	CD40103BF
CD40103BF.A	Active	Production	CDIP (J) 16	25 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	CD40103BF
CD40103BF3A	Active	Production	CDIP (J) 16	25 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	CD40103BF3A
CD40103BF3A.A	Active	Production	CDIP (J) 16	25 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	CD40103BF3A
CD40103BNSR	Active	Production	SOP (NS) 16	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-55 to 125	CD40103B
CD40103BNSR.A	Active	Production	SOP (NS) 16	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-55 to 125	CD40103B
CD40103BPW	Active	Production	TSSOP (PW) 16	90 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-55 to 125	CM0103B
CD40103BPW.A	Active	Production	TSSOP (PW) 16	90 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-55 to 125	CM0103B

⁽¹⁾ **Status:** For more details on status, see our [product life cycle](#).

⁽²⁾ **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

⁽³⁾ **RoHS values:** Yes, No, RoHS Exempt. See the [TI RoHS Statement](#) for additional information and value definition.

⁽⁴⁾ **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

⁽⁵⁾ **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

⁽⁶⁾ **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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OTHER QUALIFIED VERSIONS OF CD40103B, CD40103B-MIL :

- Catalog : [CD40103B](#)
- Military : [CD40103B-MIL](#)

NOTE: Qualified Version Definitions:

- Catalog - TI's standard catalog product
- Military - QML certified for Military and Defense Applications

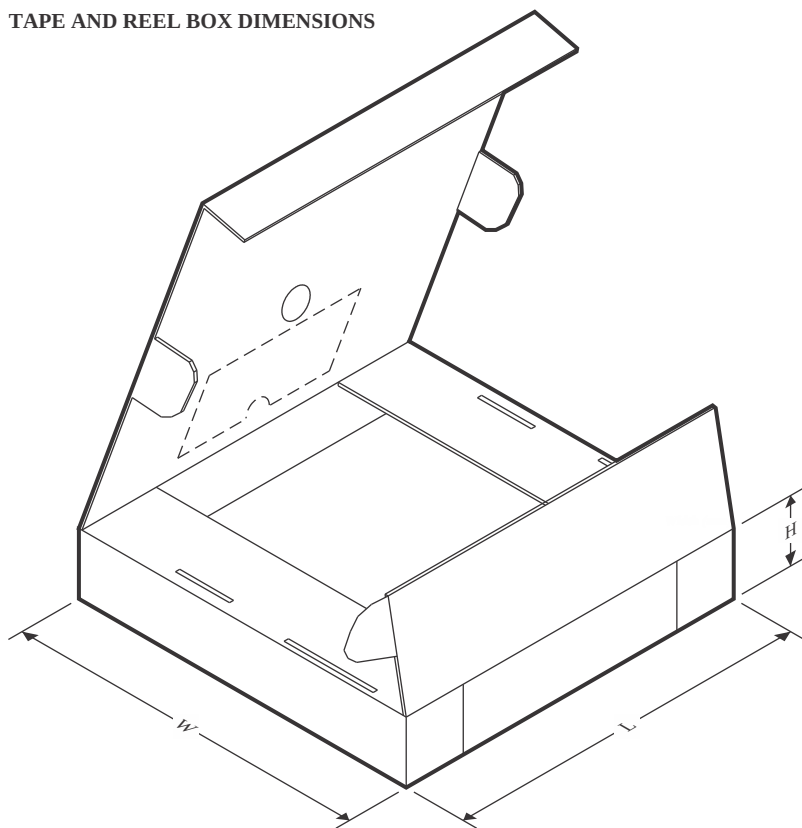
TAPE AND REEL INFORMATION



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
CD40102BPWR	TSSOP	PW	16	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
CD40103BNSR	SOP	NS	16	2000	330.0	16.4	8.1	10.4	2.5	12.0	16.0	Q1

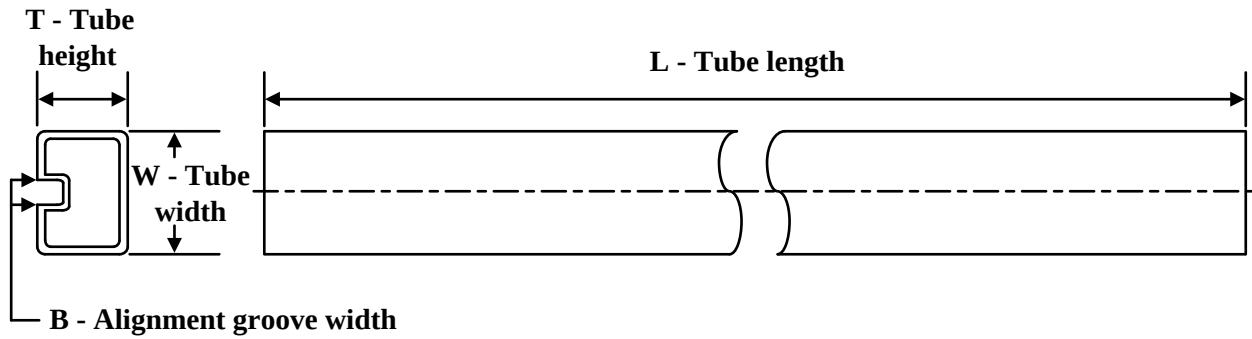
TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

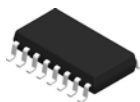
Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
CD40102BPWR	TSSOP	PW	16	2000	353.0	353.0	32.0
CD40103BNSR	SOP	NS	16	2000	353.0	353.0	32.0

TUBE



*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (μm)	B (mm)
CD40102BE	N	PDIP	16	25	506	13.97	11230	4.32
CD40102BE	N	PDIP	16	25	506	13.97	11230	4.32
CD40102BE.A	N	PDIP	16	25	506	13.97	11230	4.32
CD40102BE.A	N	PDIP	16	25	506	13.97	11230	4.32
CD40103BE	N	PDIP	16	25	506	13.97	11230	4.32
CD40103BE	N	PDIP	16	25	506	13.97	11230	4.32
CD40103BE.A	N	PDIP	16	25	506	13.97	11230	4.32
CD40103BE.A	N	PDIP	16	25	506	13.97	11230	4.32
CD40103BEE4	N	PDIP	16	25	506	13.97	11230	4.32
CD40103BEE4	N	PDIP	16	25	506	13.97	11230	4.32
CD40103BPW	PW	TSSOP	16	90	530	10.2	3600	3.5
CD40103BPW.A	PW	TSSOP	16	90	530	10.2	3600	3.5

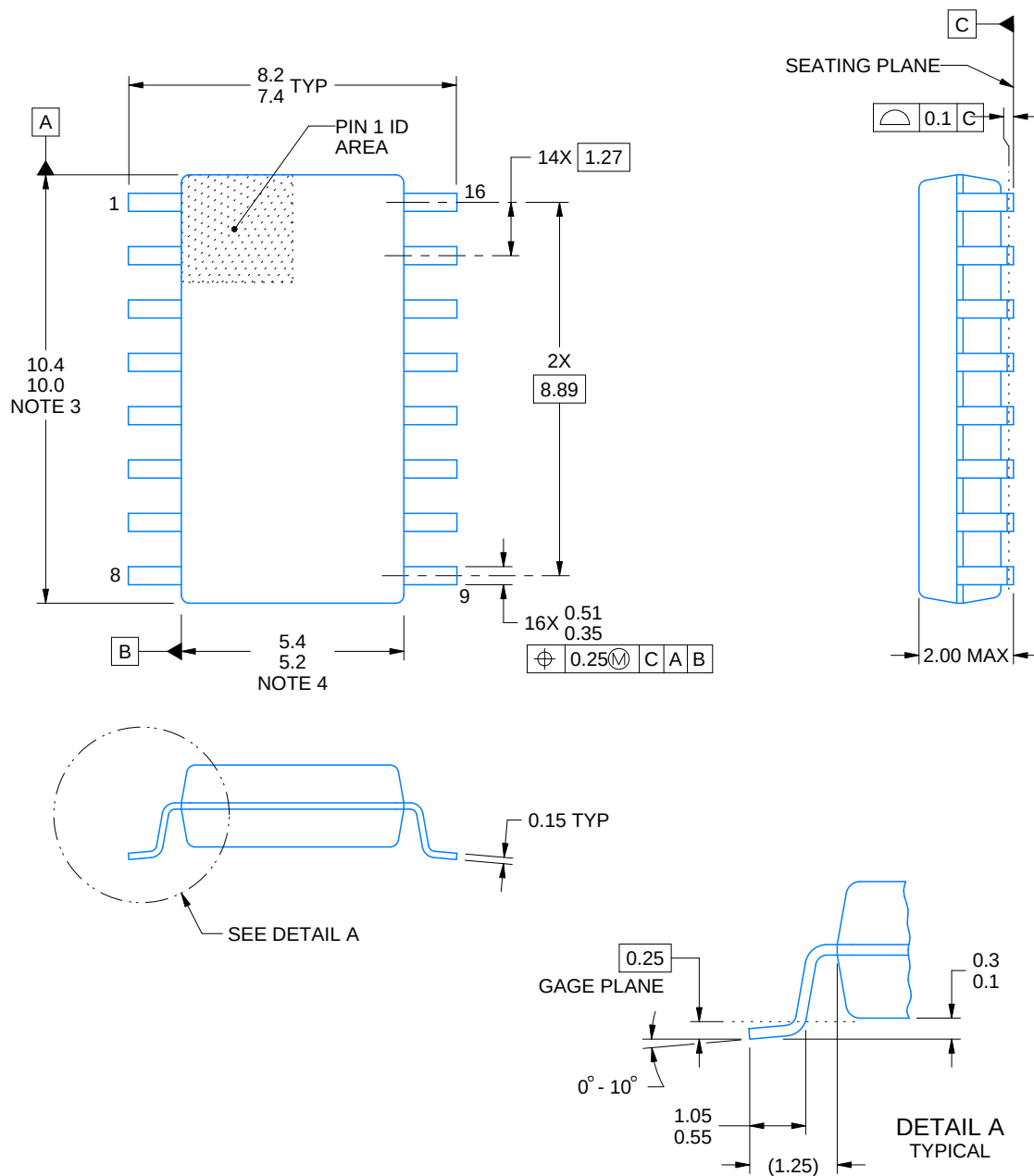


PACKAGE OUTLINE

NS0016A

SOP - 2.00 mm max height

SOP



4220735/A 12/2021

NOTES:

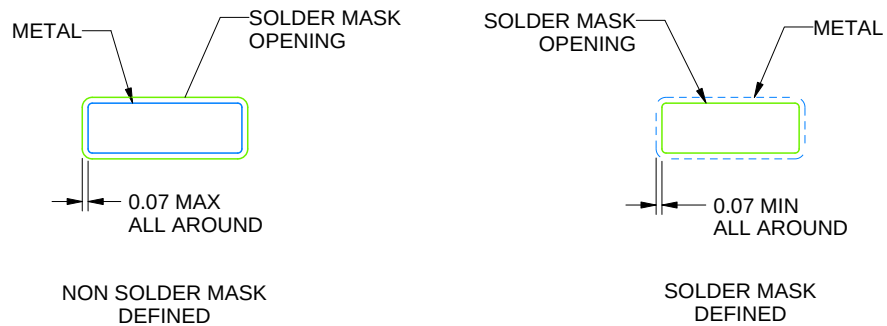
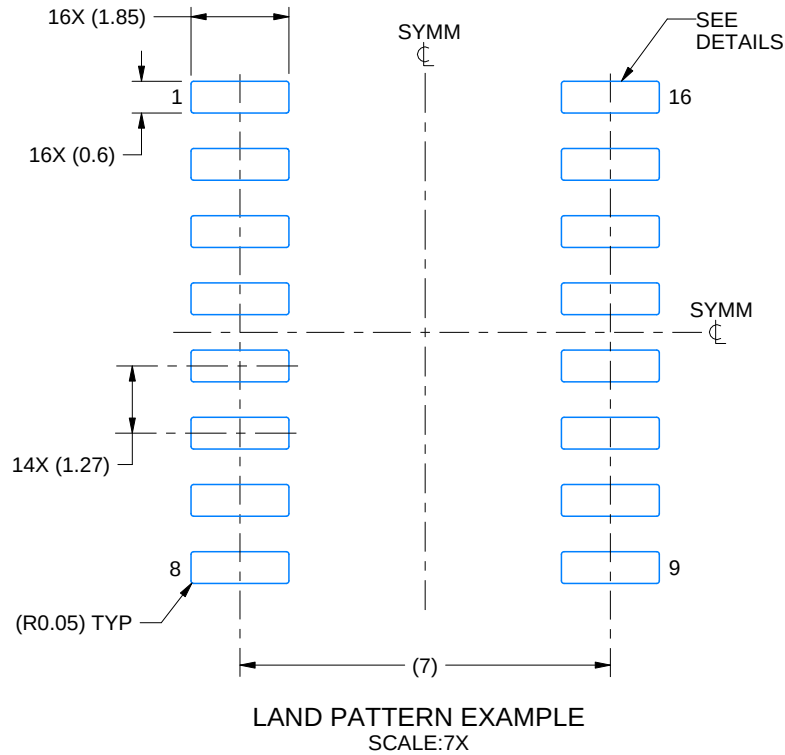
1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm, per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm, per side.

EXAMPLE BOARD LAYOUT

NS0016A

SOP - 2.00 mm max height

SOP



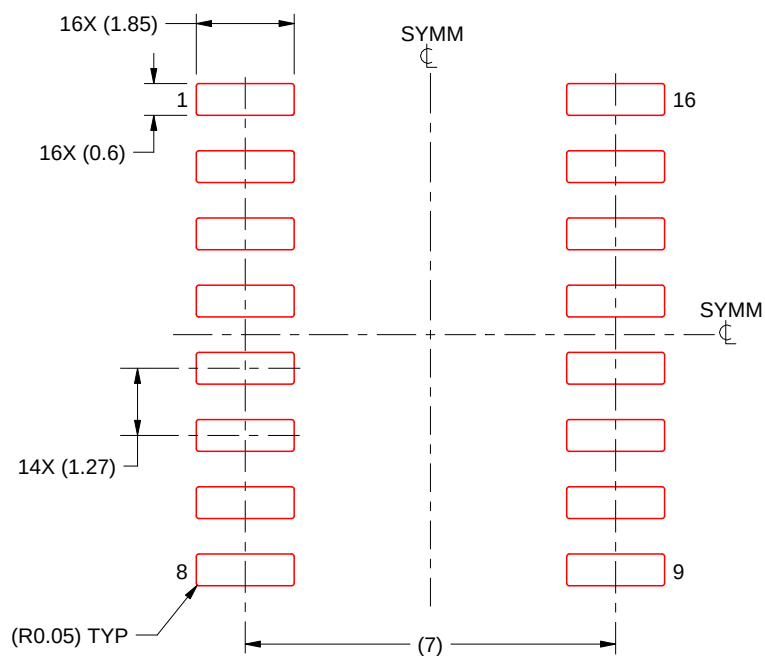
SOLDER MASK DETAILS

4220735/A 12/2021

NOTES: (continued)

5. Publication IPC-7351 may have alternate designs.

6. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SOLDER PASTE EXAMPLE
 BASED ON 0.125 mm THICK STENCIL
 SCALE:7X

4220735/A 12/2021

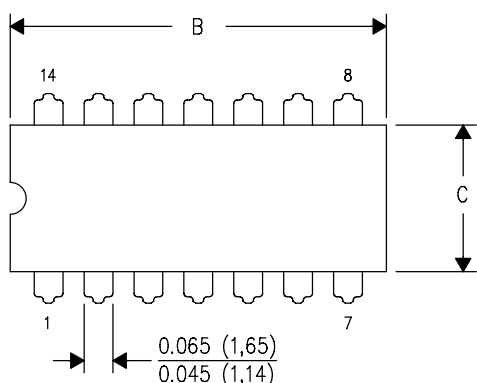
NOTES: (continued)

7. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
8. Board assembly site may have different recommendations for stencil design.

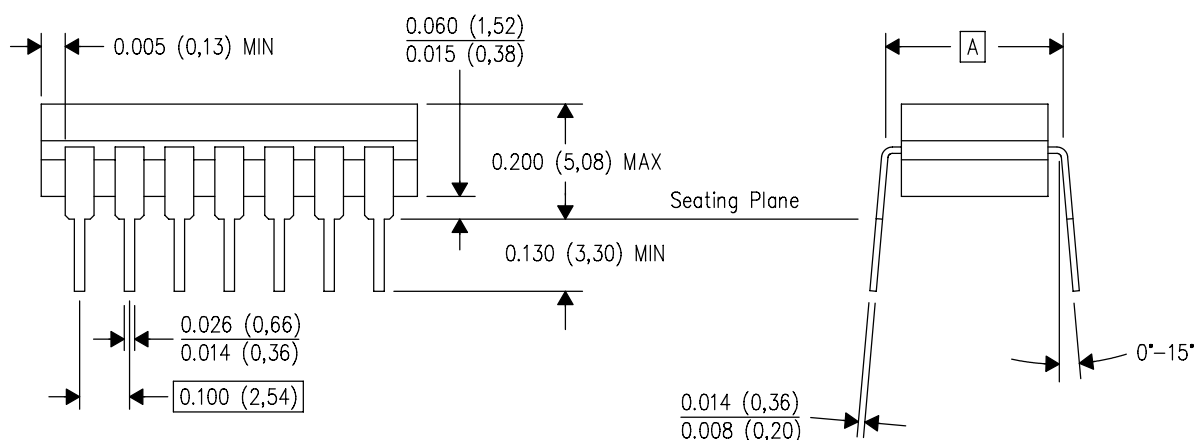
J (R-GDIP-T**)

14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE

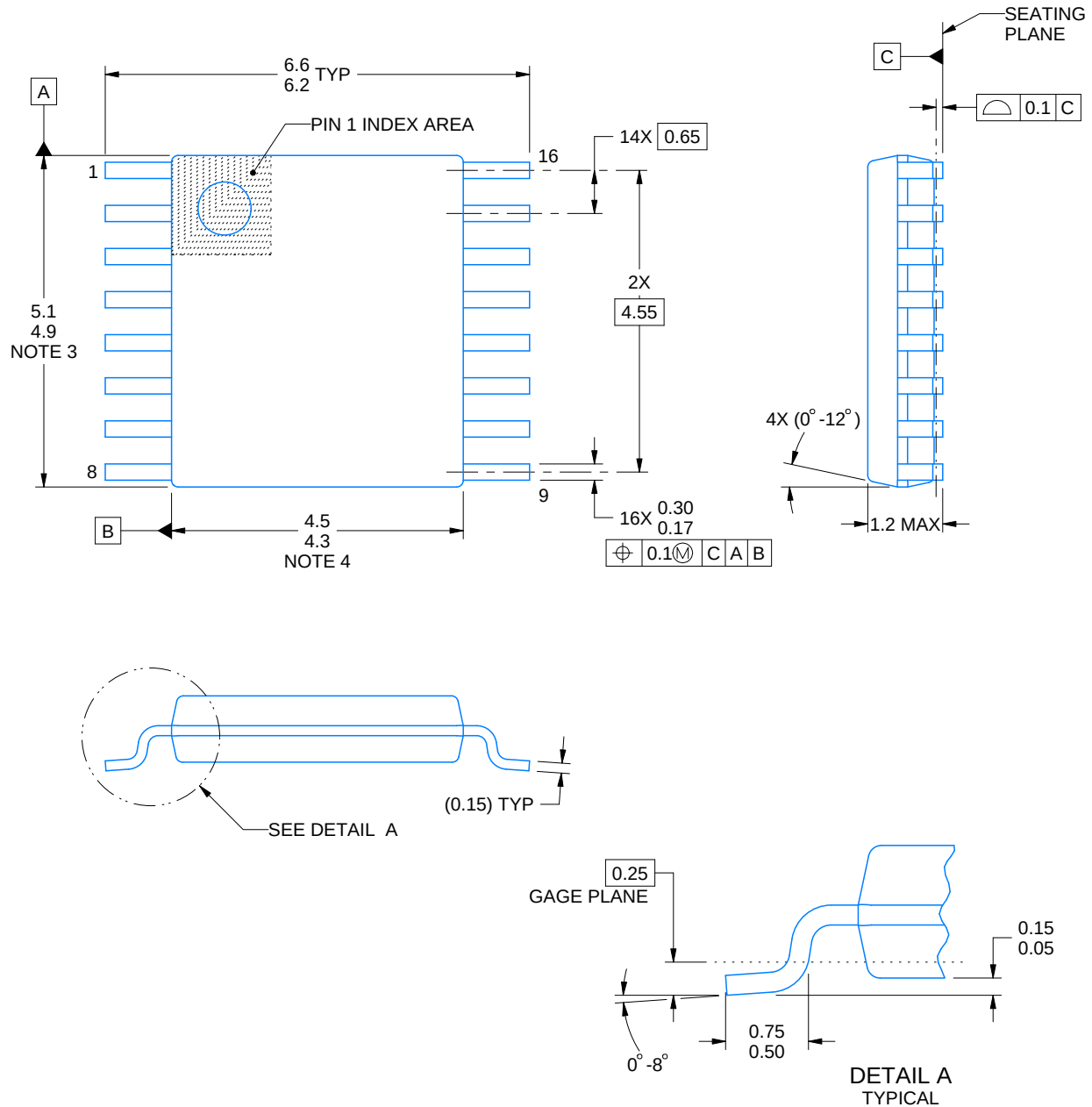
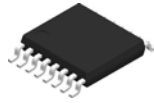


PINS ** DIM	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)



4040083/F 03/03

- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. This package is hermetically sealed with a ceramic lid using glass frit.
 - D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
 - E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.



4220204/B 12/2023

NOTES:

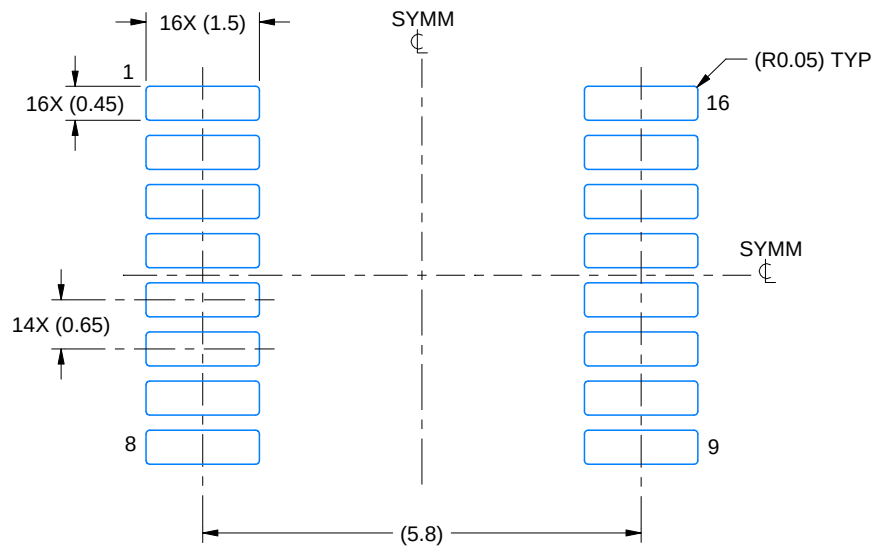
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
5. Reference JEDEC registration MO-153.

EXAMPLE BOARD LAYOUT

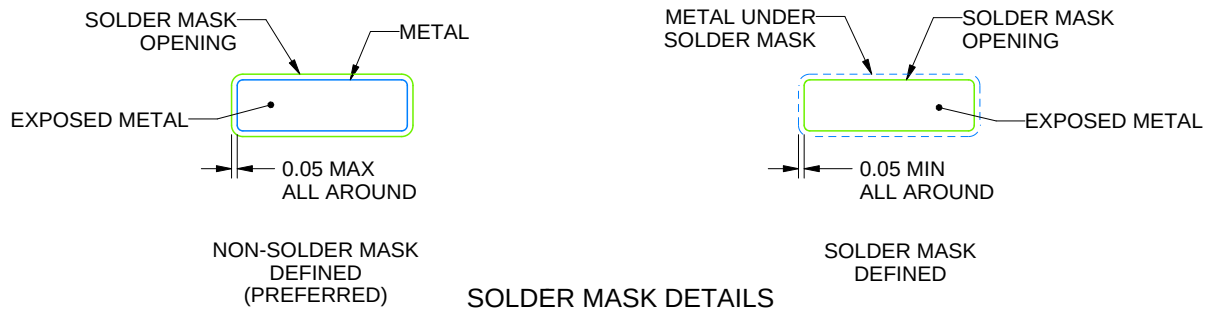
PW0016A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE: 10X



4220204/B 12/2023

NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

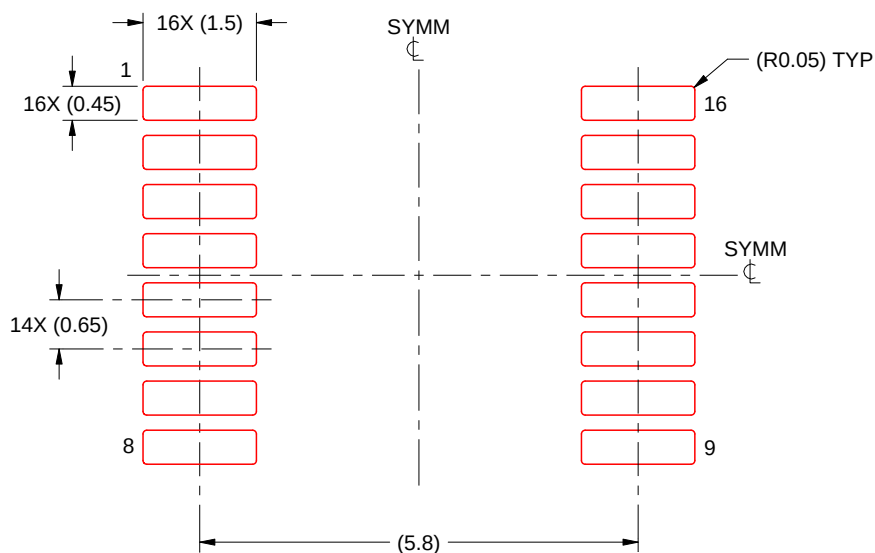
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

PW0016A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE: 10X

4220204/B 12/2023

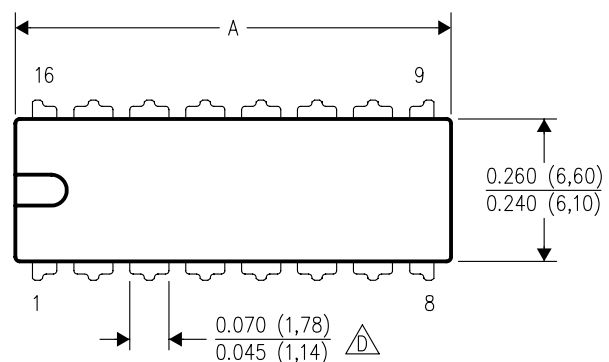
NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

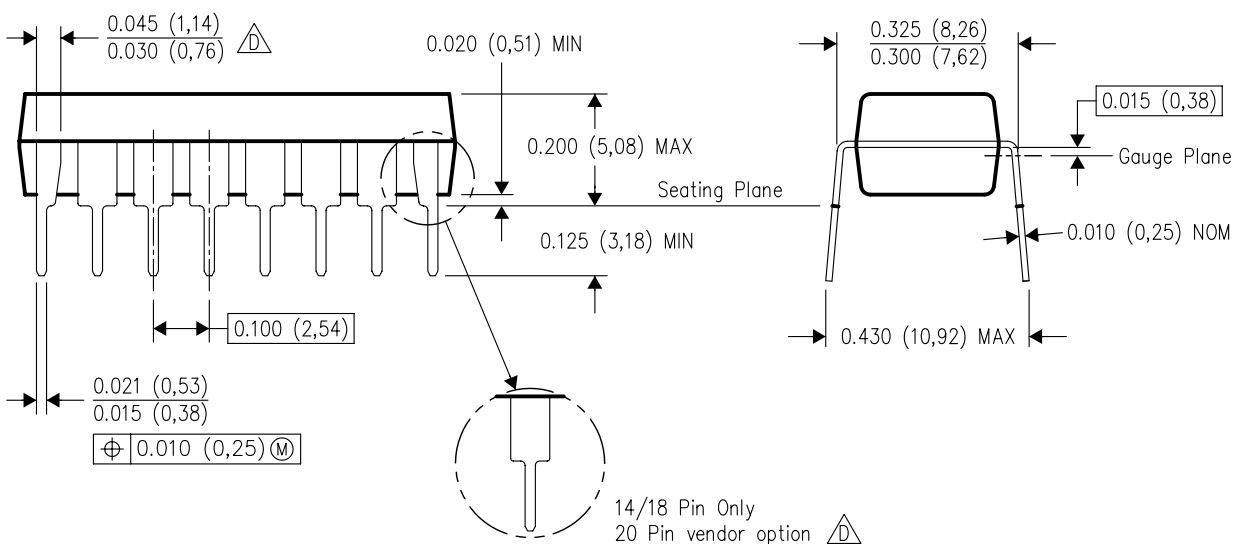
N (R-PDIP-T**)

16 PINS SHOWN

PLASTIC DUAL-IN-LINE PACKAGE



PINS ** DIM	14	16	18	20
A MAX	0.775 (19,69)	0.775 (19,69)	0.920 (23,37)	1.060 (26,92)
A MIN	0.745 (18,92)	0.745 (18,92)	0.850 (21,59)	0.940 (23,88)
MS-001 VARIATION	AA	BB	AC	AD



4040049/E 12/2002

- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 -  Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
 -  The 20 pin end lead shoulder width is a vendor option, either half or full width.

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